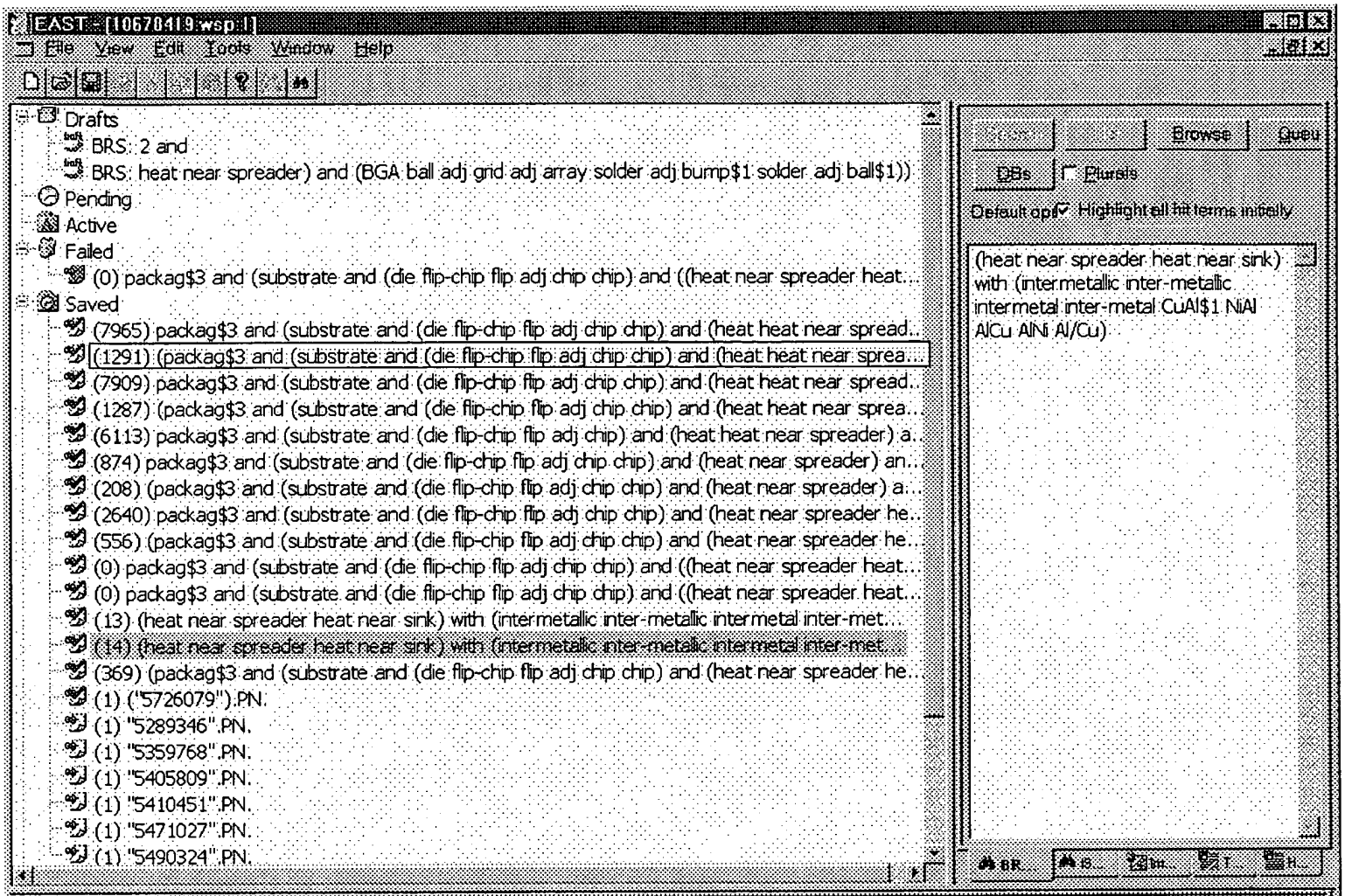

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
1	☐	☐	US 20030150595 A1	20030814	6	Structure and manufacture of a heat sink with high heat transmission	165/80.3	165/905; 257/E23.099;
2	☐	☐	US 20020191378 A1	20021219	23	Semiconductor power element heat dissipation board, and conductor plate	361/704	257/E23.106
3	☐	☐	US 20020089828 A1	20020711	23	Semiconductor power element heat dissipation board, and conductor plate	361/709	257/E23.106
4	☐	☐	US 6586279 B1	20030701	9	Method of integrating a heat spreader and a semiconductor, and package formed	438/122	257/704; 257/E23.106;
5	☐	☐	US 5708567 A	19980113	7	Ball grid array semiconductor package with ring-type heat sink	361/723	257/675; 257/E23.069;
6	☐	☐	US 5656370 A	19970812	15	Optical recording medium	428/332	369/13.38; 428/336;
7	☐	☐	US 5330701 A	19940719	10	Process for making finely divided intermetallic	419/10	419/13; 419/47;
8	☐	☐	US 4945211 A	19900731	10	Apparatus for monitoring temperature dependent changes	219/385	219/521
9	☐	☐	US 4808796 A	19890228	11	Apparatus for monitoring temperature dependent changes	219/385	219/521
10	☐	☐	US 4645116 A	19870224	7	Fluxless bonding of microelectronic chips	228/123.1	219/603;